

WHAT IS CLAIMED IS:

1. A transmission line structure on base board, in which an extra elliptical or paper-clip shaped lead-wire pattern is disposed adjacent to the output end of every independent lead wire such that the area enclosed by the lead wire can be expanded for controlling the capacitance thereof and compensating the circuit signals accordingly.
2. The structure according to Claim 1, in which first and second capacitors are formed respectively on a top and a bottom surface of the base board by a first and a second parity, in which the first capacitor is created by extending the first and second parity on the top surface of the base board to form staggeringly disposed lead-wire wound patterns, while the second capacitor is created by extending the first and second parity on the bottom surface of the base board to form staggeringly disposed lead-wire wound patterns, so that a horizontal capacitance structure is formed on the top and the bottom surface of the base board respectively, and a vertical capacitance structure is formed between the first and the second capacitor for compensating the circuit signals by enhancing the capacitance of the second and the third parity.
3. A transmission line structure on base board, in which the lead wire of a base board is composed of a plurality of signal channels; every two channels forms a parity in a paper-clip shaped lead-wire wound pattern suitably disposed on the base board; and all the parities are staggeringly disposed for controlling the capacitance in each parity and accordingly compensating the circuit signals.
4. The structure according to Claim 3, in which first and second parities form first and second capacitor on the top and the bottom surface of said base board respectively, in which the first capacitor is created by extending the first and the

second parity on the top surface of the base board to form staggeringly disposed lead-wire wound patterns while the second capacitor is created by extending the first and the second parity on the bottom surface of the base board to form staggeringly disposed lead-wire wound patterns, namely, said first and said second parity form a horizontal capacitance structure on the top surface and the bottom surface of the base board respectively, and a vertical capacitance structure is also formed by the first and the second capacitor to thereby enhance the capacitance between the second parity and the third parity for compensating the circuit signals.